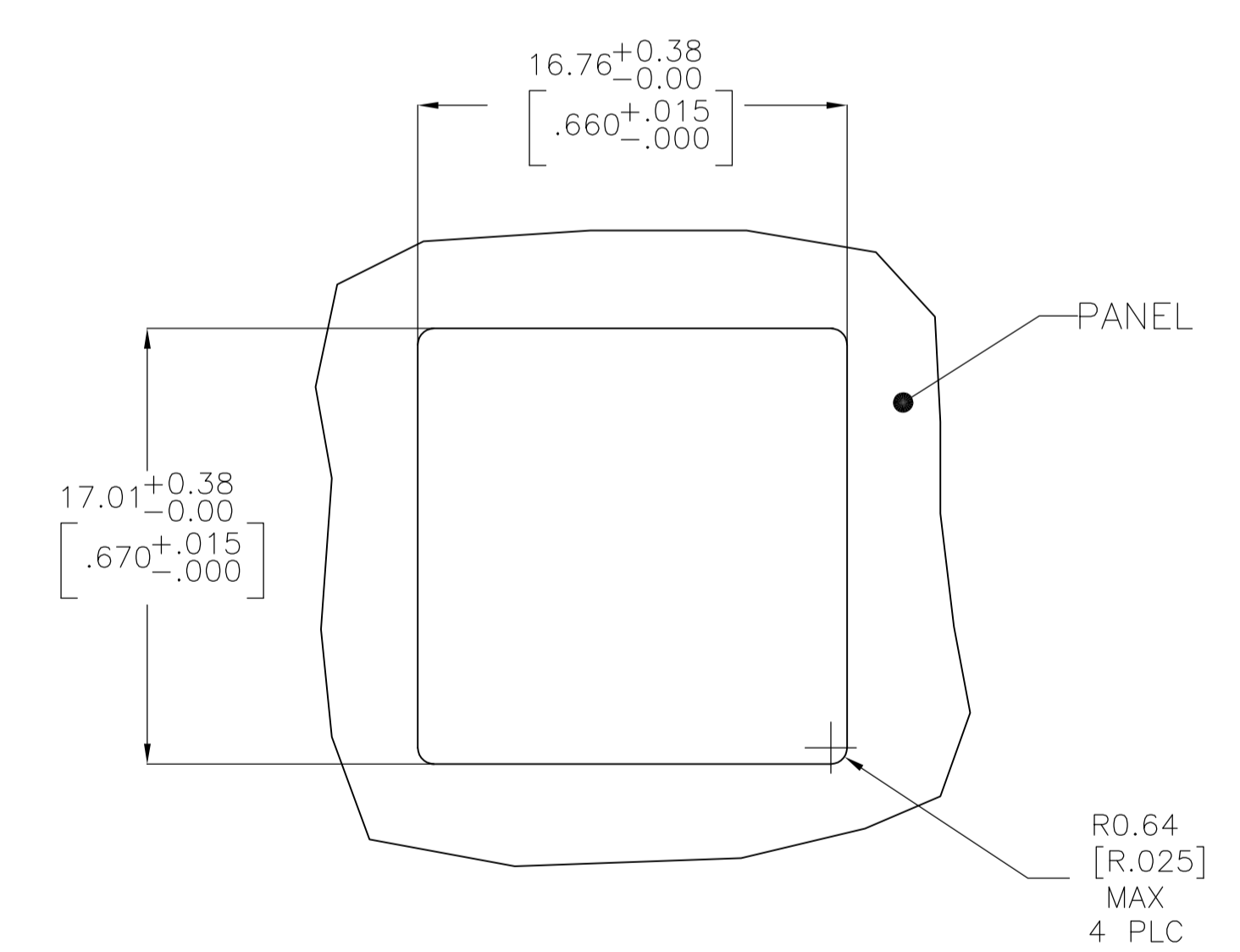


RECOMMENDED PRINTED
CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN



RECOMMENDED PANEL
CUTOUT

- MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0μm [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

1888412-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. STRAUSSER / L.A. MAYER 07MAR2006		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 07MAR2006 NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, KEYED WITH PANEL STOPS, PANEL AND PCB GROUNDS	
0 PLC ± -		1 PLC ± -		PRODUCT SPEC 108-1163	
2 PLC ± -		3 PLC ± 0.13(.005)		APPLICATION SPEC 114-2048	
4 PLC ± -		ANGLES ± -		SIZE CAGE CODE DRAWING NO A1 00779 C=1888412	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		WEIGHT -	
				CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV B	